

PESD3V3V4UK; PESD5V0V4UK; PESD9V0V4UK

Very low capacitance unidirectional quadruple ESD protection diode arrays

Rev. 1 — 25 August 2010

Product data sheet

1. Product profile

1.1 General description

Very low capacitance unidirectional quadruple ElectroStatic Discharge (ESD) protection diode arrays in a leadless ultra small SOT891 Surface-Mounted Device (SMD) plastic package designed to protect up to four unidirectional signal lines from the damage caused by ESD and other transients.

1.2 Features and benefits

- ESD protection of up to four lines
- Very low diode capacitance
- Max. peak pulse power: $P_{PP} = 28 \text{ W}$
- Low clamping voltage: $V_{CL} = 9.5 \text{ V}$
- AEC-Q101 qualified
- Very low leakage current: $I_{RM} = 0.1 \mu\text{A}$
- ESD protection up to 15 kV
- IEC 61000-4-2; level 4 (ESD)
- IEC 61000-4-5 (surge); $I_{PP} = 2.7 \text{ A}$

1.3 Applications

- Computers and peripherals
- Audio and video equipment
- Cellular handsets and accessories
- Communication systems
- Portable electronics
- Subscriber Identity Module (SIM) card protection

1.4 Quick reference data

Table 1. Quick reference data

$T_{amb} = 25 \text{ }^\circ\text{C}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Per diode						
V_{RWM}	reverse standoff voltage					
	PESD3V3V4UK		-	-	3.3	V
	PESD5V0V4UK		-	-	5.0	V
	PESD9V0V4UK		-	-	9.0	V

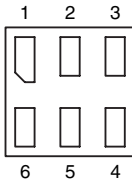
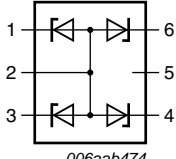


Table 1. Quick reference data ...continued
T_{amb} = 25 °C unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
C _d	diode capacitance	f = 1 MHz; V _R = 0 V				
	PESD3V3V4UK		-	13	17	pF
	PESD5V0V4UK		-	12	15	pF
	PESD9V0V4UK		-	6.5	10	pF

2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	cathode (diode 1)	 <p>bottom view</p>	 <p>006aab474</p>
2	common anode		
3	cathode (diode 2)		
4	cathode (diode 3)		
5	not connected		
6	cathode (diode 4)		

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PESD3V3V4UK	-	plastic extremely thin small outline package; no leads; 6 terminals; body 1 × 1 × 0.5 mm	SOT891
PESD5V0V4UK			
PESD9V0V4UK			

4. Marking

Table 4. Marking codes

Type number	Marking code
PESD3V3V4UK	P1
PESD5V0V4UK	P2
PESD9V0V4UK	P3

5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
Per diode					
P _{PP}	peak pulse power	t _p = 8/20 μs	[1][2] -		
	PESD3V3V4UK PESD5V0V4UK		-	25	W
	PESD9V0V4UK		-	28	W
I _{PP}	peak pulse current	t _p = 8/20 μs	[1][2] -		
	PESD3V3V4UK		-	2.7	A
	PESD5V0V4UK		-	2.5	A
	PESD9V0V4UK		-	1.5	A
Per device					
T _j	junction temperature		-	150	°C
T _{amb}	ambient temperature		-55	+150	°C
T _{stg}	storage temperature		-65	+150	°C

[1] Non-repetitive current pulse 8/20 μs exponential decay waveform according to IEC 61000-4-5.

[2] Measured from pin 1, 3, 4, or 6 to pin 2.

Table 6. ESD maximum ratings

T_{amb} = 25 °C unless otherwise specified.

Symbol	Parameter	Conditions	Min	Max	Unit
Per diode					
V _{ESD}	electrostatic discharge voltage	IEC 61000-4-2 (contact discharge)	[1][2]		
	PESD3V3V4UK		-	10	kV
	PESD5V0V4UK		-	15	kV
	PESD9V0V4UK		-	8	kV
	PESDxV4UK series	machine model	[2] -	400	V
	PESDxV4UK series	MIL-STD-883 (human body model)	-	8	kV

[1] Device stressed with ten non-repetitive ESD pulses.

[2] Measured from pin 1, 3, 4 or 6 to pin 2.

Table 7. ESD standards compliance

Standard	Conditions
Per diode	
IEC 61000-4-2; level 4 (ESD)	> 15 kV (air); > 8 kV (contact)
MIL-STD-883; class 3 (human body model)	> 4 kV

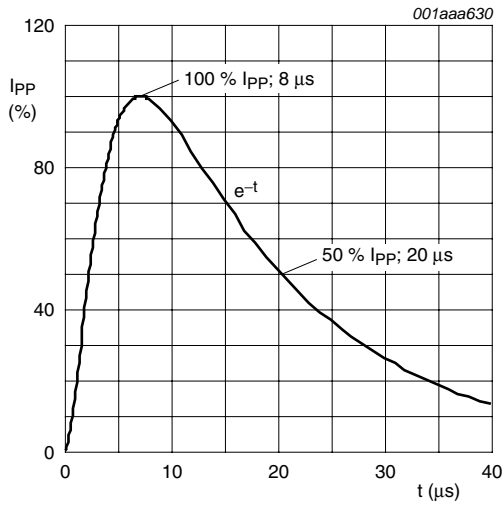


Fig 1. 8/20 μs pulse waveform according to IEC 61000-4-5

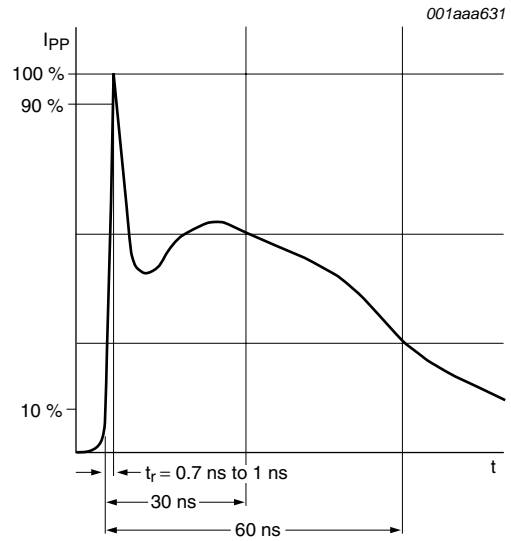


Fig 2. ESD pulse waveform according to IEC 61000-4-2

6. Characteristics

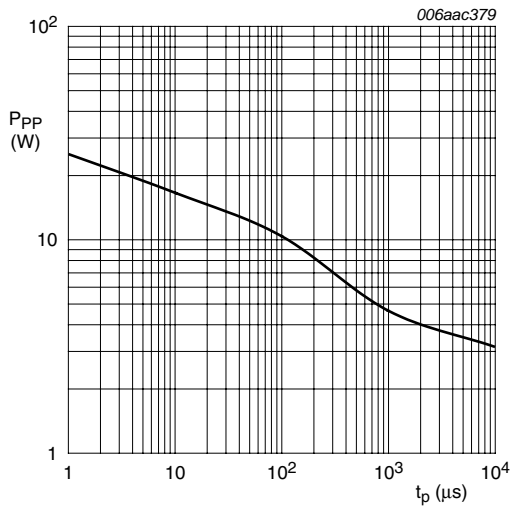
Table 8. Characteristics

$T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Per diode						
V_{RWM}	reverse standoff voltage					
	PESD3V3V4UK		-	-	3.3	V
	PESD5V0V4UK		-	-	5.0	V
	PESD9V0V4UK		-	-	9.0	V
I_{RM}	reverse leakage current					
	PESD3V3V4UK	$V_{RWM} = 3.3\text{ V}$	-	0.13	1	μA
	PESD5V0V4UK	$V_{RWM} = 5.0\text{ V}$	-	0.05	0.3	μA
	PESD9V0V4UK	$V_{RWM} = 9.0\text{ V}$	-	0.003	0.1	μA
V_{BR}	breakdown voltage	$I_R = 1\text{ mA}$				
	PESD3V3V4UK		5.3	5.6	5.9	V
	PESD5V0V4UK		6.47	6.8	7.14	V
	PESD9V0V4UK		11.4	12	12.7	V
C_d	diode capacitance	$f = 1\text{ MHz};$ $V_R = 0\text{ V}$				
	PESD3V3V4UK		-	13	17	pF
	PESD5V0V4UK		-	12.5	15	pF
	PESD9V0V4UK		-	6.5	10	pF
V_{CL}	clamping voltage		[1] [2]			
	PESD3V3V4UK	$I_{PP} = 2.6\text{ A}$	-	-	9.5	V
	PESD5V0V4UK	$I_{PP} = 2.4\text{ A}$	-	-	10	V
	PESD9V0V4UK	$I_{PP} = 1.5\text{ A}$	-	-	19	V
r_{dif}	differential resistance	$I_R = 5\text{ mA}$				
	PESD3V3V4UK		-	5	16	Ω
	PESD5V0V4UK		-	2.5	8	Ω
	PESD9V0V4UK		-	10	30	Ω

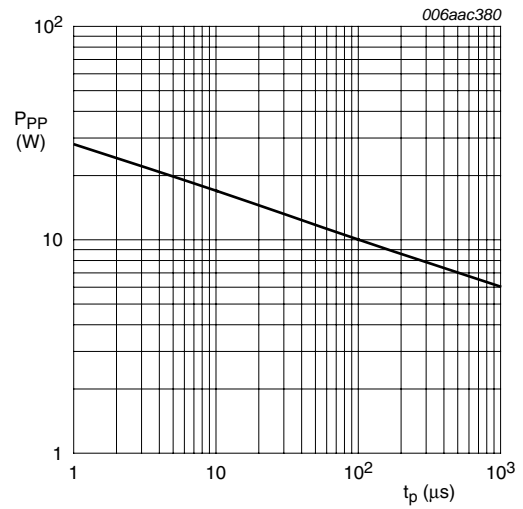
[1] Non-repetitive current pulse 8/20 μs exponential decay waveform according to IEC 61000-4-5.

[2] Measured from pin 1, 3, 4 or 6 to pin 2.



$T_{amb} = 25\text{ }^\circ\text{C}$
 (1) PESD3V3V4UK
 (2) PESD5V0V4UK

Fig 3. Peak pulse power as a function of exponential pulse duration; typical values



$T_{amb} = 25\text{ }^\circ\text{C}$
 (1) PESD9V0V4UK

Fig 4. Peak pulse power as a function of exponential pulse duration; typical values

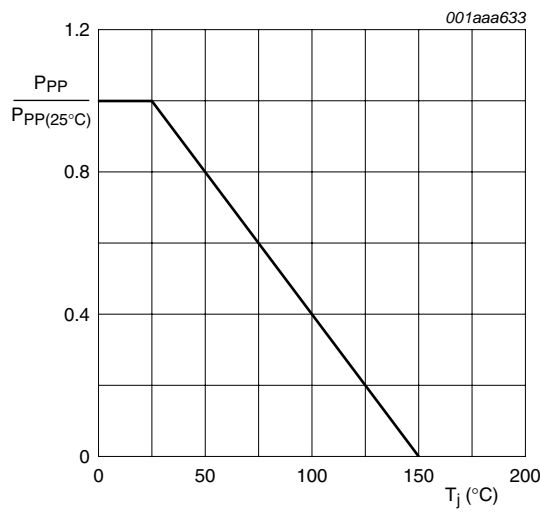
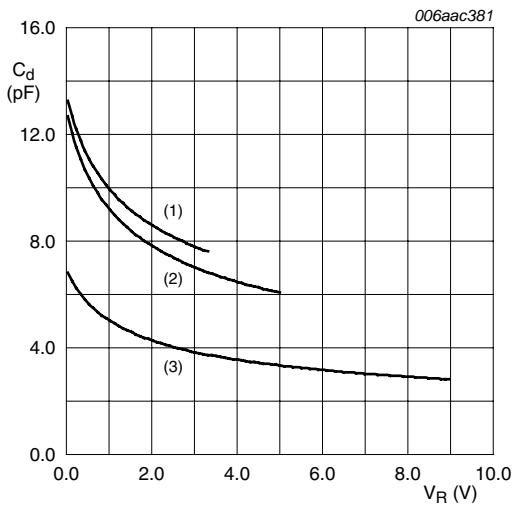
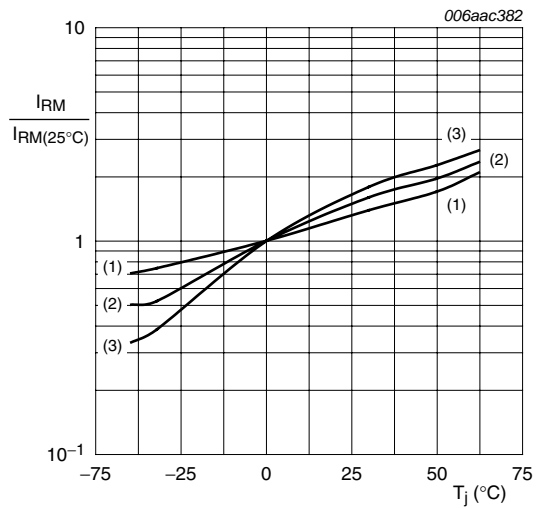


Fig 5. Relative variation of peak pulse power as a function of junction temperature; typical values



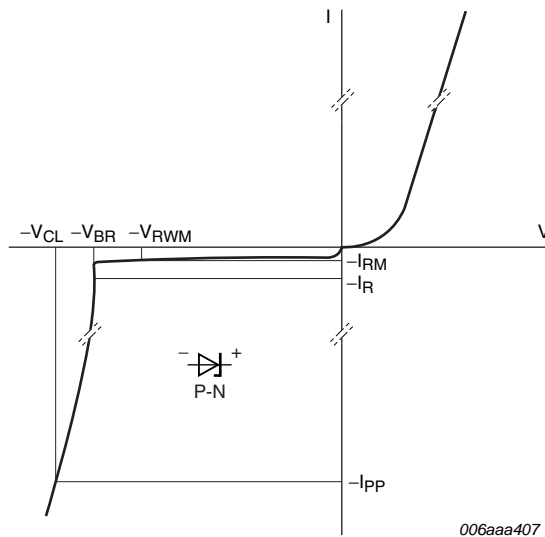
$f = 1 \text{ MHz}; T_{\text{amb}} = 25 \text{ }^\circ\text{C}$
 (1) PESD3V3V4UK
 (2) PESD5V0V4UK
 (3) PESD9V0V4UK

Fig 6. Diode capacitance as a function of reverse voltage; typical values



(1) PESD3V3V4UK
 (2) PESD5V0V4UK
 (3) PESD9V0V4UK

Fig 7. Relative variation of reverse leakage current as a function of junction temperature; typical values



006aaa407

Fig 8. V-I characteristics for a unidirectional ESD protection diode

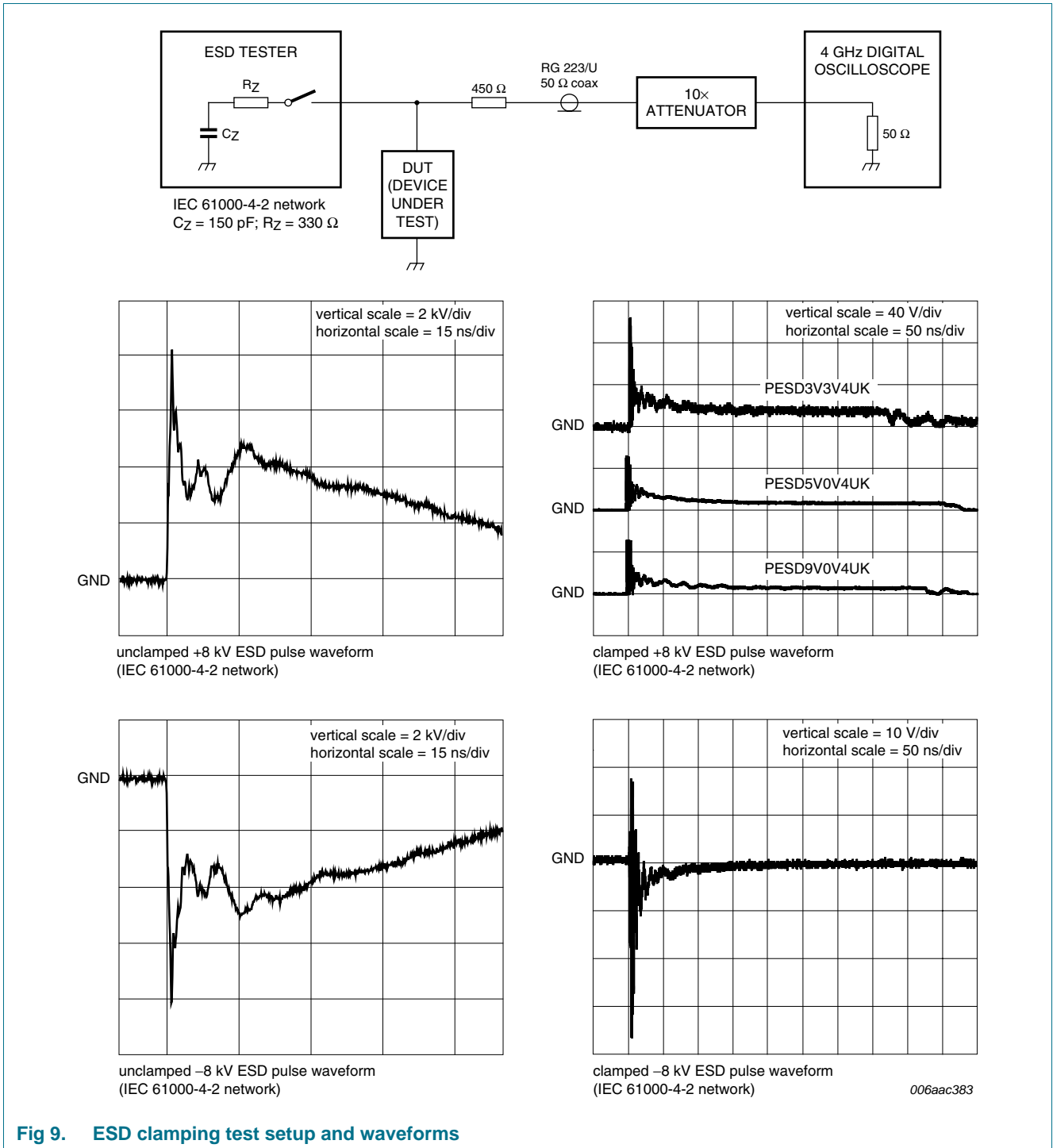


Fig 9. ESD clamping test setup and waveforms

7. Application information

The PESDxV4UK series is designed for the protection of up to four unidirectional data or signal lines from the damage caused by ESD and surge pulses. The devices may be used on lines where the signal polarities are either positive or negative with respect to ground. The PESD3V3V4UK and the PESD5V0V4UK provide a surge capability of 25 W per line and the PESD9V0V4UK provides a surge capability of 28 W per line for an 8/20 μ s waveform.

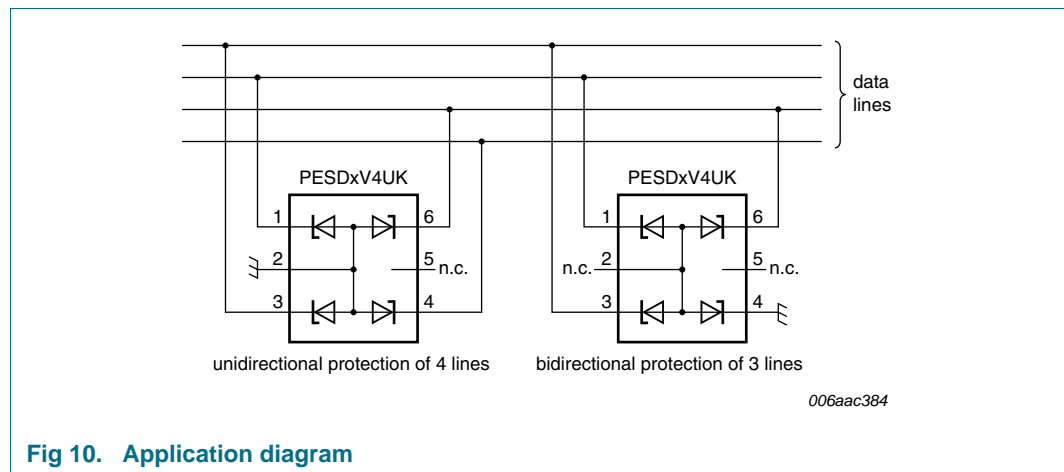


Fig 10. Application diagram

Circuit board layout and protection device placement

Circuit board layout is critical for the suppression of ESD, Electrical Fast Transient (EFT) and surge transients. The following guidelines are recommended:

1. Place the device as close to the input terminal or connector as possible.
2. The path length between the device and the protected line should be minimized.
3. Keep parallel signal paths to a minimum.
4. Avoid running protected conductors in parallel with unprotected conductors.
5. Minimize all Printed-Circuit Board (PCB) conductive loops including power and ground loops.
6. Minimize the length of the transient return path to ground.
7. Avoid using shared transient return paths to a common ground point.
8. Ground planes should be used whenever possible. For multilayer PCBs, use ground vias.

8. Test information

8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - *Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

9. Package outline

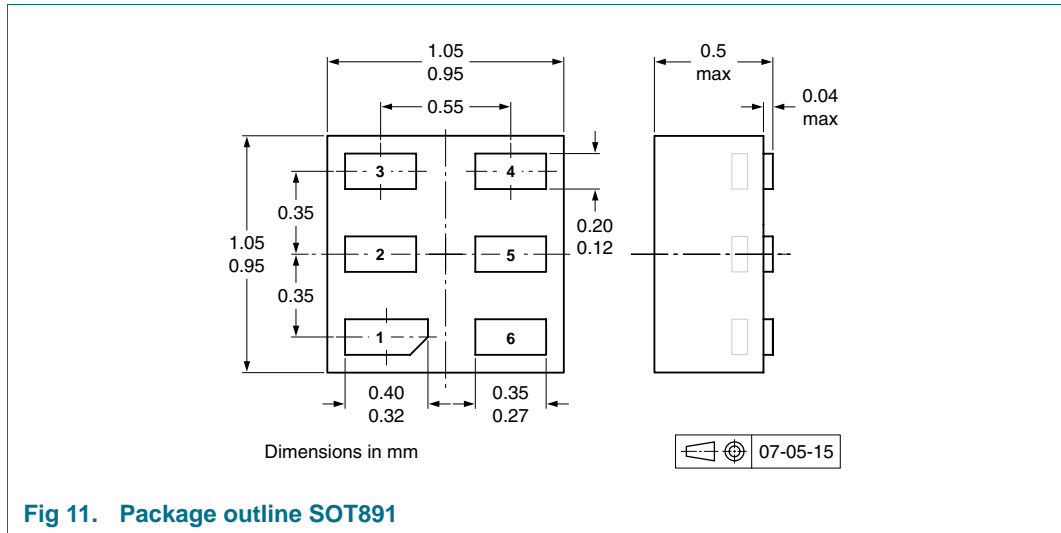


Fig 11. Package outline SOT891

10. Packing information

Table 9. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.^[1]

Type number	Package	Description	Packing quantity
			5000
PESD3V3V4UK	SOT891	4 mm pitch, 8 mm tape and reel; T4	^[2] -132
PESD5V0V4UK			
PESD9V0V4UK			

[1] For further information and the availability of packing methods, see [Section 14](#).

[2] T4: 90° rotated reverse taping

12. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PESDXV4UK_SER v.1	20100825	Product data sheet	-	-

13. Legal information

13.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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Date of release: 25 August 2010

Document identifier: PESDXV4UK_SER